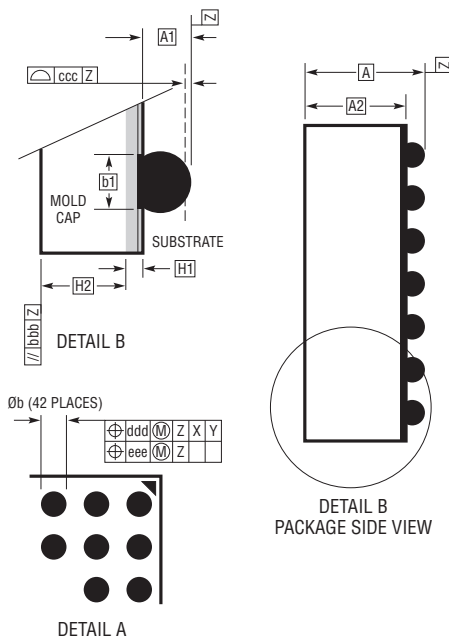
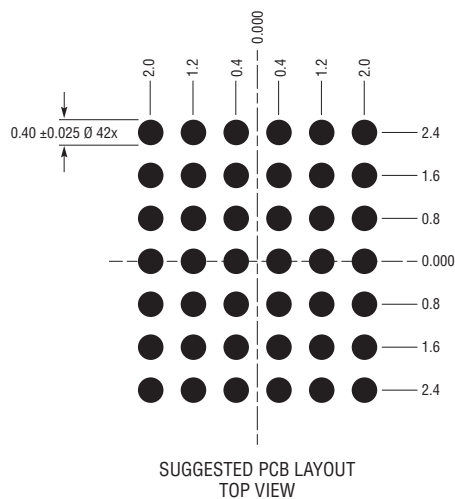
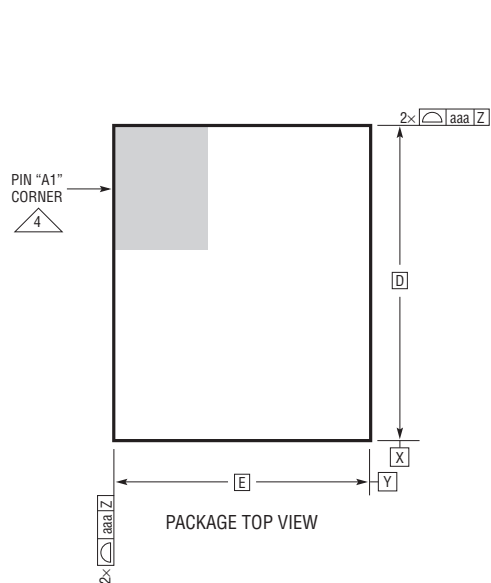
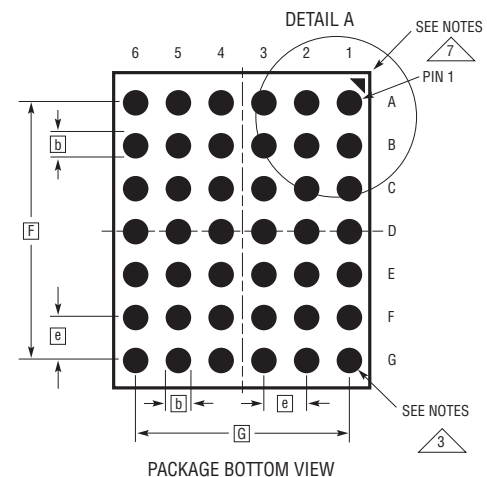


**BGA Package**  
**42-Lead (6mm × 5mm × 1.30mm)**  
 (Reference LTC DWG # 05-08-1515 Rev A)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.10	1.30	1.50	
A1	0.30	0.40	0.50	BALL HT
A2	0.80	0.90	1.00	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		6.00		
E		5.00		
e		0.80		
F		4.80		
G		4.00		
H1	0.15	0.20	0.25	SUBSTRATE THK
H2	0.65	0.70	0.75	MOLD CAP HT
aaa			0.15	
bbb			0.20	
ccc			0.20	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 42				



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC

7 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

